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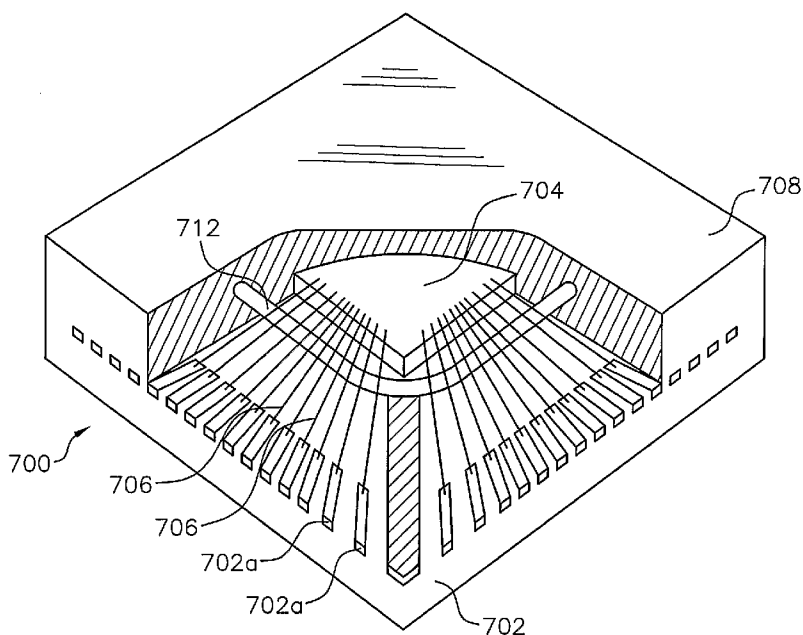
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(54) Title: SYSTEM AND METHOD FOR REDUCING OR ELIMINATING SEMICONDUCTOR DEVICE WIRE SWEEP



(57) Abstract: A method of packaging a semiconductor device is provided. The method includes applying an insulative material across only a portion of at least two of a plurality of conductors providing interconnection between elements in the semiconductor device. The method also includes encapsulating the conductors and elements, thereby packaging the semiconductor device.

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